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## **MICROBONDS EXPANDS MANAGEMENT TEAM**

**TORONTO, Canada**, July 12<sup>th</sup>, 2005 - Microbonds, Inc., a private Canadian company that has developed a pioneering insulated wire bonding technology (X-Wire™ Technology) today announced the appointments of Tim Smith as VP, Worldwide Sales & Marketing and William (Bud) Crockett, Jr. as Manager of Customer Applications.

Tim brings an extensive, 20-year background in high-technology semiconductor, SOC, IP sales and service at the die level, as well as a broad range of international sales and management experience across North America, Europe and Asia. Tim will be based in California's Silicon Valley.

Bud has over nine years of international expertise in the packaging assembly & test industry, most recently with STATSChipPac, with direct working experience across the full spectrum of packaging technologies (e.g. BGA, Leadframe, FlipChip, etc.) and a special focus on new packaging technologies. Bud will also be located in Silicon Valley.

Microbonds' X-Wire Technology enables chip designers and packagers to achieve superior performance to cost electronic connections across a wide spectrum of chip designs and packages.

"Tim and Bud are welcome additions to our management team as we accelerate the introduction of our technology into the global marketplace," said Craig Geier, CEO of Microbonds. "Tim's broad experience in high-end SOC technology targeted at the more advanced single and multi-chip designs in the market, complimented by Bud's extensive experience at addressing the requirements for new packaging technologies, makes them a very valuable resource for our customers and our company."

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Prior to joining Microbonds, Tim was Vice President, Worldwide Sales at Sonics Inc., a successful supplier of IP interconnect solutions for complex handheld and consumer digital SOCs including cell phones, digital TVs, game platforms and WiFi. Previously, Tim was the Vice President of Sales at Triscend Corporation, a provider of configurable SOC platforms that was recently sold to Xilinx, Inc. In addition, Tim founded and managed Memec Design Services, a global supplier of services and IP for large gate-count Xilinx FPGAs. He has held various engineering, marketing and sales positions at leading communications and semiconductor test companies following his graduation from Arizona State University with a Bachelors Degree in Electrical Engineering.

After graduation from California Polytechnic State College and following eight years of service with the U.S. Navy, Bud began his private sector career in the microelectronics field with Strausburgh Inc., a world-class supplier to the Semiconductor Industry. Over the last six years, Bud worked in varying capacities at one of the leading IC Assembly & Test Companies, STATSChipPac, most recently as New Product Introduction Manager.

### **About Microbonds**

Microbonds, Inc. is a pioneer in the development of unique microchip-interconnect solutions for use in the design and assembly of microelectronic devices. The company's X-Wire Technology enables the development of faster, smaller and cheaper microchips while improving manufacturing reliability. Founded in 1999 by IBM-trained engineers, the company's approach is demonstrated through testing with major IC companies. Microbonds is a privately held company funded by a leading Canadian VC, Whitecap Venture Partners and a group of private global angel investors. For more information, see [www.microbonds.com](http://www.microbonds.com)

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